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October 2014

FDMA86551L

Single N-Channel PowerTrench® MOSFET

60 V, 7.5 A, 23 mΩ

Features

- Max $r_{DS(on)} = 23 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 7.5 \text{ A}$
- Max $r_{DS(on)}$ = 35 m Ω at V_{GS} = 4.5 V, I_D = 6 A
- Low Profile 0.8 mm maximum in the new package MicroFET
- Free from halogenated compounds and antimony oxides
- RoHS Compliant

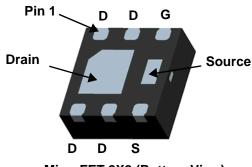


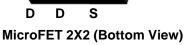
General Description

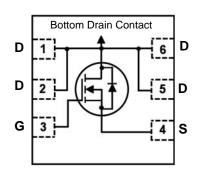
This device has been designed to provide maximum efficiency and thermal performance for synchronous buck converters. The low rDS(on) and gate charge provide excellent switching performance.

Application

■ DC – DC Buck Converters







MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Paramete	er		Ratings	Units
V _{DS}	Drain to Source Voltage			60	V
V _{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T _A = 25 °C	(Note 1a)	7.5	^
'D	-Pulsed		(Note 4)	45	A
Eas	Single Pulse Avalanche Energy		(Note 3)	37	mJ
D	Power Dissipation	T _A = 25 °C	(Note 1a)	2.4	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1b)	0.9	VV
T _J , T _{STG}	Operating and Storage Junction Temperatu	re Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	145	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
551	FDMA86551L	MicroFET 2X2	7 "	8 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions		Тур	Max	Units
Off Chara	cteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		31		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 48 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.8	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-5		mV/°C
	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$		19	23	
		$V_{GS} = 4.5 \text{ V}, I_D = 6 \text{ A}$		26	35	mΩ
r _{DS(on)}	Static Brain to Source On Nesistance	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A},$ $T_J = 125 ^{\circ}\text{C}$		28	33	11122
9 _{FS}	Forward Transconductance	$V_{DD} = 5 \text{ V}, I_{D} = 7.5 \text{ A}$		21		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 00 V V 0 V		881	1235	pF
C _{oss}	Output Capacitance	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz		182	255	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12		6.1	15	pF
R_g	Gate Resistance		0.1	0.5	1.5	Ω

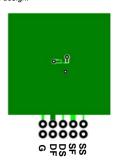
Switching Characteristics

t _{d(on)}	Turn-On Delay Time	.,,	7.3	15	ns
t _r	Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 7.5 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	1.7	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6.12$	16	29	ns
t _f	Fall Time		1.4	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 V to 10 V	12	17	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 30 \text{ V}$,	5.8	8.1	nC
Q_{gs}	Gate to Source Charge	I _D = 7.5 A	2.7	3.8	nC
Q _{qd}	Gate to Drain "Miller" Charge		1.4	2.0	nC

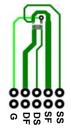
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$	(Note 2)	0.8	1.2	V
	Source to Drain Diode Forward voltage	$V_{GS} = 0 \text{ V}, I_{S} = 7.5 \text{ A}$	(Note 2)	0.9	1.2	V
t _{rr}	Reverse Recovery Time	I _E = 7.5 A, di/dt = 100 A	\/us	23	37	ns
Q_{rr}	Reverse Recovery Charge	$I_F = 7.5 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{S}$		9.7	19	nC

^{1.} R_{8JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{8JC} is guaranteed by design while R_{8JA} is determined by the user's board design.



a. 52 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 145 °C/W when mounted on a minimum pad of 2 oz copper.

^{2.} Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%.
3. E_{AS} of 37 mJ is based on starting T_J = 25 °C, L = 3 mH, I_{AS} = 5 A, V_{DD} = 60 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 16 A.

^{4.} Pulse Id measured at td <= 250 $\mu s,$ refer to Fig 11 SOA graph for more details.

Typical Characteristics T_J = 25 °C unless otherwise noted

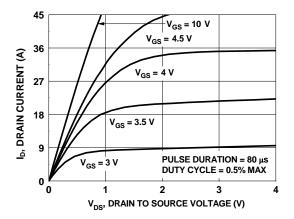


Figure 1. On-Region Characteristics

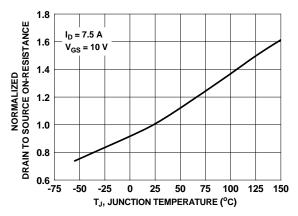


Figure 3. Normalized On-Resistance vs Junction Temperature

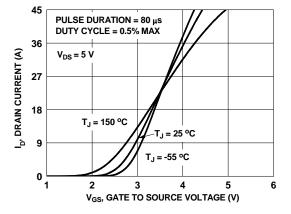


Figure 5. Transfer Characteristics

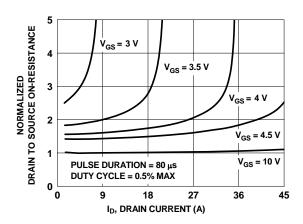


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

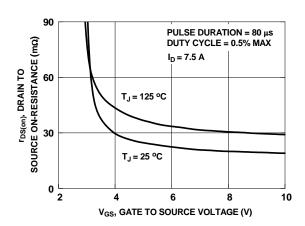


Figure 4. On-Resistance vs Gate to Source Voltage

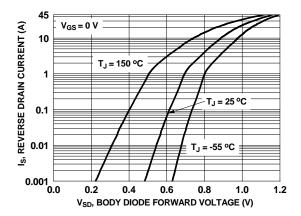


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

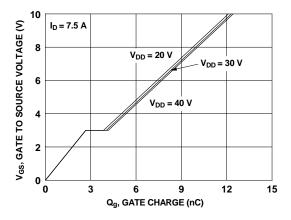


Figure 7. Gate Charge Characteristics

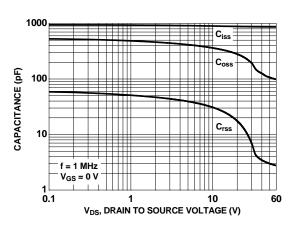


Figure 8. Capacitance vs Drain to Source Voltage

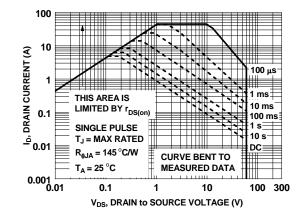


Figure 9. Forward Bias Safe Operating Area

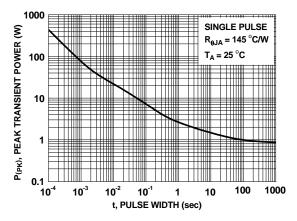


Figure 10. Single Pulse Maximum Power Dissipation

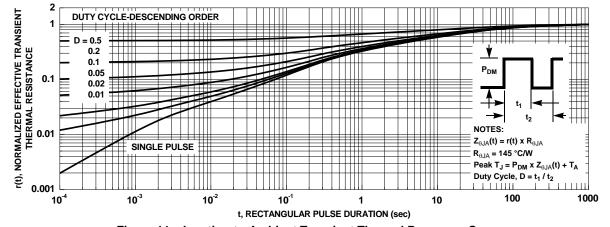
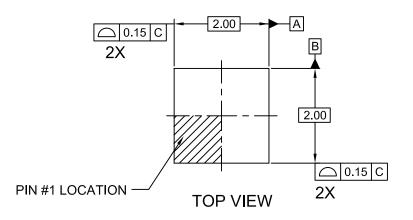
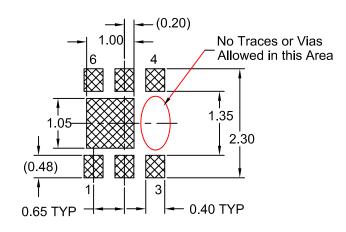
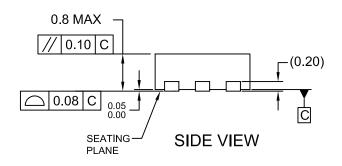


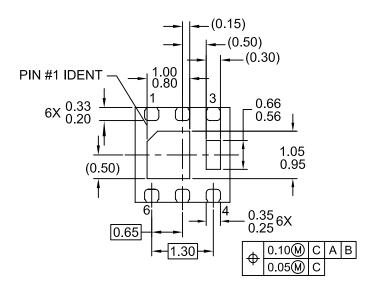
Figure 11. Junction-to-Ambient Transient Thermal Response Curve

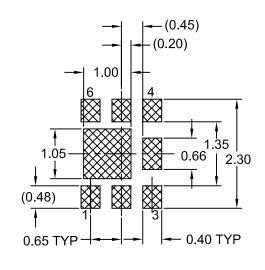




RECOMMENDED LAND PATTERN OPT 1







RECOMMENDED LAND PATTERN OPT 2

NOTES:

A. DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-229 DATED AUG/2003

BOTTOM VIEW

- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. DRAWING FILENAME: MKT-MLP06Prev1.

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